# INTEGRATED CIRCUITS



Product specification

1990 Oct 04

IC15 Data Handbook





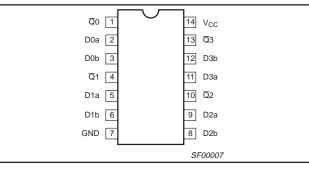
74F02

## **FEATURE**

Industrial temperature range available (-40°C to +85°C)

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F02	3.4ns	4.4mA

### **PIN CONFIGURATION**



## **ORDERING INFORMATION**

DESCRIPTION	C	RDER CODE	
DESCRIPTION	COMMERCIAL RANGE $V_{CC}$ = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	INDUSTRIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = −40°C to +85°C	PKG DWG #
14-pin plastic DIP	N74F02N	174F02N	SOT27-1
14-pin plastic SO	N74F02D	I74F02D	SOT108-1

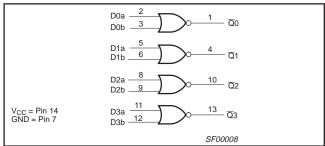
# INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

PINS	DESCRIPTION	DESCRIPTION 74F (U.L.) HIGH/LOW			
Dna, Dnb	Data inputs	1.0/1.0	20µA/0.6mA		
Qn	Data output	50/33	1.0mA/20mA		

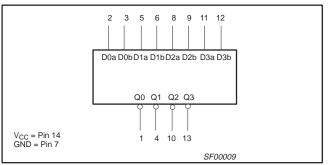
#### NOTE:

One (1.0) FAST unit load is defined as:  $20\mu A$  in the high state and 0.6mA in the low state.

### LOGIC DIAGRAM



## LOGIC SYMBOL



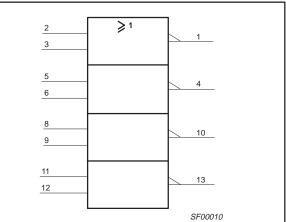
### **FUNCTION TABLE**

INP	JTS	OUTPUT
Dna	Dnb	Qn
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

NOTES:

1 H = High voltage level 2 L = Low voltage level

## **IEC/IEEE SYMBOL**



74F02

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limit set forth in this table may impair the useful life of the device.

Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA	
V <sub>OUT</sub>	Voltage applied to output in high output state	–0.5 to $V_{CC}$	V	
I <sub>OUT</sub>	Current applied to output in low output state		40	mA
T <sub>amb</sub>	Operating free air temperature range	Commercial range	0 to +70	°C
		Industrial range	-40 to +85	°C
T <sub>stg</sub>	Storage temperature range		-65 to +150	°C

## **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER			LIMITS		UNIT
			MIN	NOM	MAX	1
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V	
V <sub>IL</sub>	Low-level input voltage			0.8	V	
I <sub>lk</sub>	Input clamp current				-18	mA
I <sub>OH</sub>	High-level output current				-1	mA
I <sub>OL</sub>	Low-level output current				20	mA
T <sub>amb</sub>	Operating free air temperature range	Commercial range	0		+70	°C
		Industrial range	-40		+85	°C

### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIO	NS <sup>1</sup>		LIMITS		UNIT	
					MIN	TYP <sup>2</sup>	MAX		
V <sub>OH</sub>	High-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>	2.5			V	
			V <sub>IH</sub> = MIN, I <sub>OH</sub> = MAX	±5%V <sub>CC</sub>	2.7	3.4		V	
V <sub>OL</sub>	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>		0.30	0.50	V	
			V <sub>IH</sub> = MIN, I <sub>OI</sub> = MAX	±5%V <sub>CC</sub>		0.30	0.50	V	
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$			-0.73	-1.2	V	
l	Input current at maximum voltage	input	$V_{CC} = MAX, V_I = 7.0V$				100	μΑ	
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ	
IIL	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA	
I <sub>OS</sub>	Short-circuit output curren	ıt <sup>3</sup>	V <sub>CC</sub> = MAX	-60		-150	mA		
I <sub>CC</sub>	Supply current (total) <sup>4</sup>	I <sub>CCH</sub>	V <sub>CC</sub> = MAX			3.0	5.6	mA	
		I <sub>CCL</sub>	V <sub>CC</sub> = MAX		7.0	13.0	mA		

NOTES:

1 For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2

All typical values are at  $V_{CC} = 5V$ ,  $T_{amb} = 25^{\circ}C$ . Not more than one output should be shorted at a time. For testing  $I_{OS}$ , the use of high-speed test apparatus and/or sample-and-hold 3 techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

4 I<sub>CC</sub> is measured with outputs open.

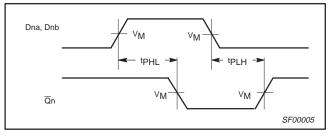
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# AC ELECTRICAL CHARACTERISTICS

				LIMITS								
SYMBOL	PARAMETER	TEST CONDITION	V <sub>CC</sub> = +5.0V T <sub>amb</sub> = +25°C C <sub>L</sub> = 50pF, R <sub>L</sub> = 500Ω			T <sub>amb</sub> = 0°0	0V ± 10% C to +70°C R <sub>L</sub> = 500Ω	V <sub>CC</sub> = +5. T <sub>amb</sub> = -40° C <sub>L</sub> = 50pF,	UNIT			
			MIN	TYP	MAX	MIN	MAX	MIN	MAX			
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Dna, Dnb to Qn	Waveform 1	2.5 2.0	4.4 3.2	5.5 4.3	2.5 2.0	6.5 5.3	2.5 1.5	7.0 6.0	ns		

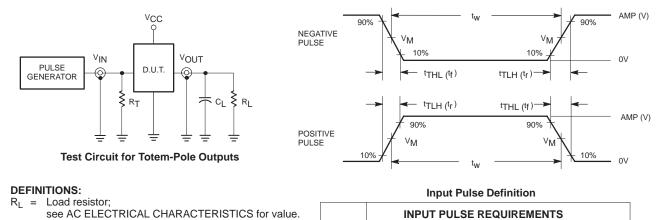
## **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ .



Waveform 1. Propagation delay for inverting outputs

# **TEST CIRCUIT AND WAVEFORM**

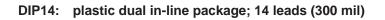


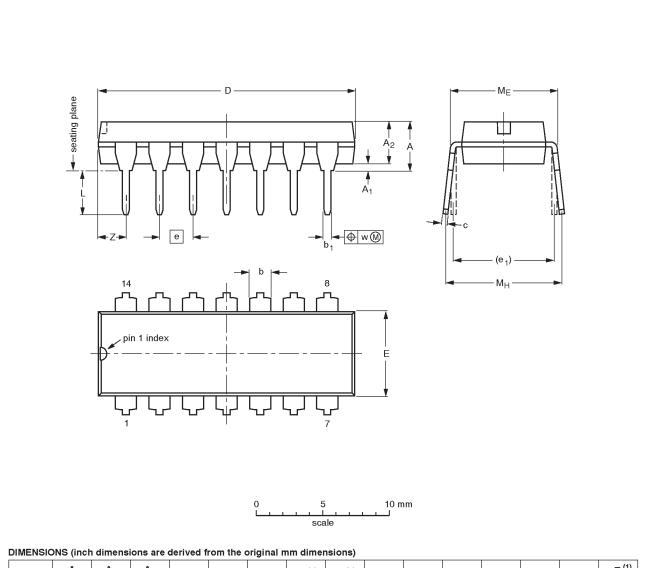
- $C_L = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.$
- $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

fomily	INPUT PULSE REQUI			REMENIS					
family	amplitude	VM	rep. rate	tw	t <sub>TLH</sub>	t <sub>THL</sub>			
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns			

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# Quad 2-input NOR gate





UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	Μ <sub>E</sub>	м <sub>н</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

### Note

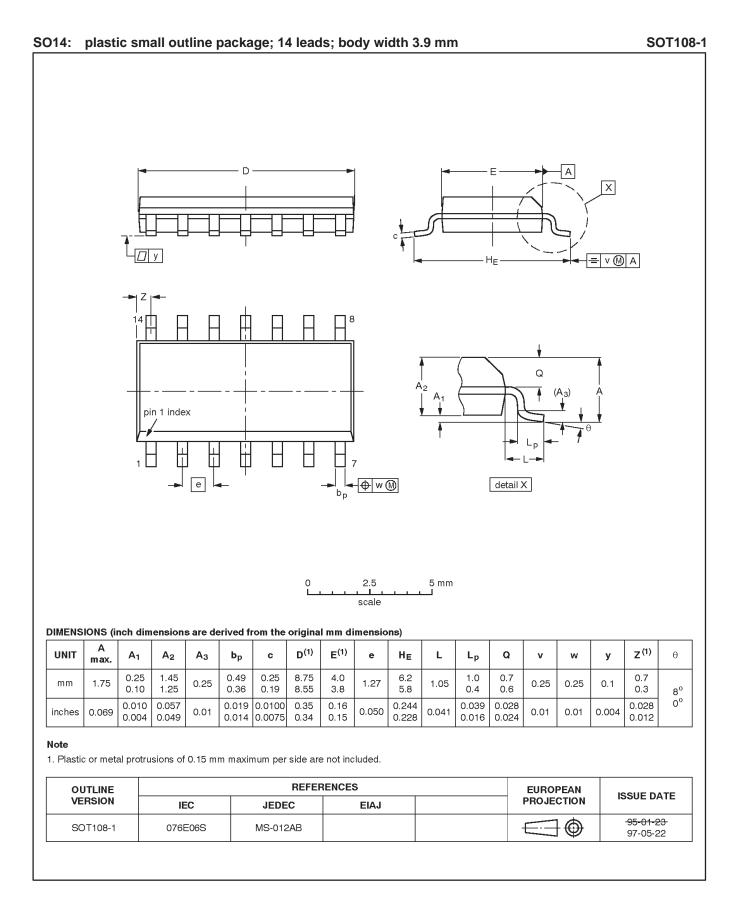
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE				
VERSION	IEC	JEDEC	EIAJ		PROJECTION	1550E DATE		
SOT27-1	050G04	MO-001AA				<del>-92-11-17</del> 95-03-11		

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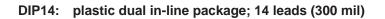


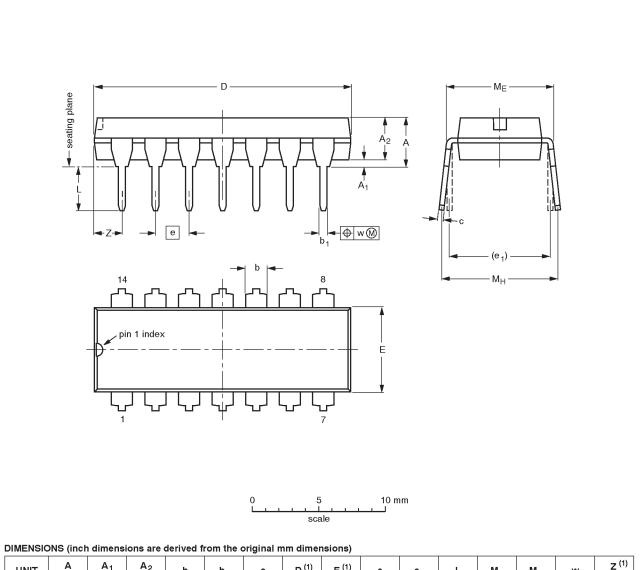
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NOTES

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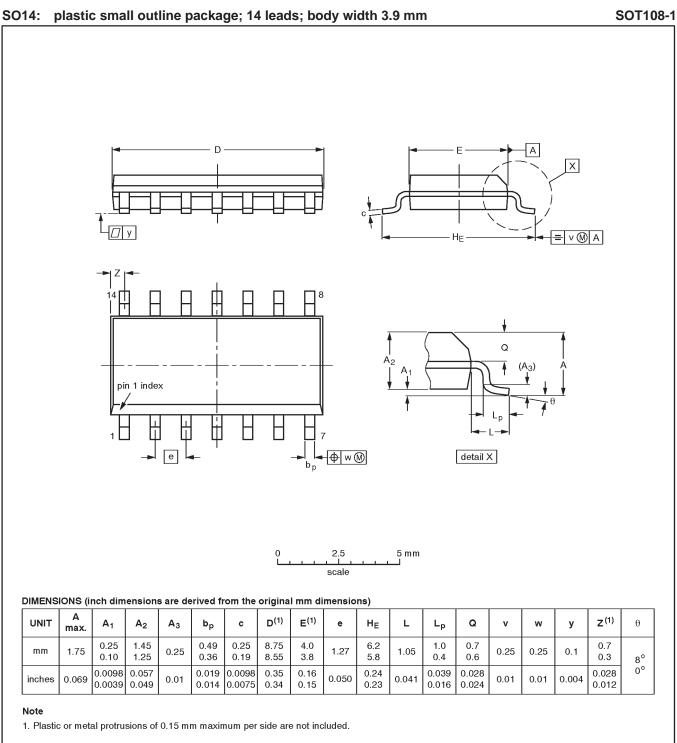
OUTLINE	REFERENCES				EUROPEAN	
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SOT27-1

Product specification

74F02



OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06\$	MS-012AB				<del>91-08-13-</del> 95-01-23

74F02

NOTES

# 74F02

DEFINITIONS					
Data Sheet Identification	Product Status	Definition			
Objective Specification Formative or in Design		This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.			
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.			
Product Specification Full Production		This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.			

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